



Material Content Data Sheet



Sales Product Name	TLT807B0EPV			Issued	24. January 2018			
MA#	MA001624870							
Package	PG-TSDSO-14-1			Weight*	64.10 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.910	2.98	2.98	29799	29799
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		146	
	non noble metal	zinc	7440-66-6	0.037	0.06		582	
	non noble metal	iron	7439-89-6	0.746	1.16		11645	
wire	non noble metal	copper	7440-50-8	30.306	47.29	48.52	472821	485194
	non noble metal	copper	7440-50-8	0.058	0.09	0.09	902	902
	encapsulation	organic material	carbon black	1333-86-4	0.086	0.13		1338
encapsulation	plastics	epoxy resin	-	3.344	5.22		52169	
	inorganic material	silicondioxide	60676-86-0	25.150	39.24	44.59	392382	445889
leadfinish	non noble metal	tin	7440-31-5	1.644	2.57	2.57	25651	25651
plating	noble metal	silver	7440-22-4	0.135	0.21	0.21	2105	2105
glue	plastics	epoxy resin	-	0.168	0.26		2615	
	noble metal	silver	7440-22-4	0.503	0.78	1.04	7845	10460
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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